

# Metal Composite Power Inductor (Thin Film)

# **Specification Sheet**



## CIGT252010LMR33MNE (2520 / EIA 1008)

**APPLICATION** 

Smart phones, Tablet, Wearable devices, Power converter modules, etc.

#### **FEATURES**

Small power inductor for mobile devices Low DCR structure and high efficiency inductor for power circuits. Monolithic structure for high reliability Free of all RoHS-regulated substances Halogen free

#### DIMENSION



#### DESCRIPTION

Part no.	Size	Thickness	Inductance	Inductance tolerance (%)	DC Resistance [mΩ]		Rated DC Current (Isat) [A]		Rated DC Current (Irms) [A]	
	[inch/mm] [mm] (	[mm] (max)	[mm] (max) [uH]		Max.	Тур.	Max.	Тур.	Max.	Тур.
CIGT252010LMR33MNE	1008/2520	1.0	0.33	±20	22	17	6.5	7.3	5	5.5

\* Inductance : Measured with a LCR meter 4991A(Agilent) or equivalent (Test Freq. 1MHz, Level 0.1V)

\* DC Resistance : Measured with a Resistance HI-TESTER 3541(HIOKI) or equivalent

\* Maximum allowable DC current : Value defined when DC current flows and the initial value of inductance has decreased by 30% or

when current flows and temperature has risen to 40 °C whichever is smaller. (Reference: ambient temperature is 25 °C±10) (Isat) : Allowable current in DC saturation : The DC saturation allowable current value is specified when the decrease of

the initial inductance value at 30% (Reference: ambient temperature is 25  $^\circ$ C±10)

(Irms) : Allowable current of temperature rise : The temperature rise allowable current value is specified when temperature of the inductor is raised 40 °C by DC current. (Reference: ambient temperature is 25 °C±10)

\* Absolute maximum voltage : Absolute maximum voltage DC 20V.

\* Operating temperature range : -40 to +125°C (Including self-temperature rise)

PRODUCT IDENTIFICATION

CIG	T	<u>2520</u>	<u>10</u>	LM	<u>R33</u>	M	<u>N</u>	<u>E</u>
		(3)						

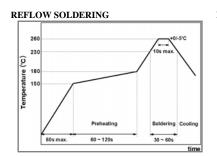
- (1) Power Inductor
- (3) Dimensior (2520: 2.5mm × 2.0mm )
- (5) Remark (Characterization Code)
- (7) Toleranc (M:±20%)
- (8) Internal Code

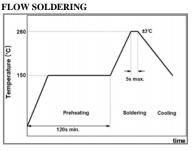
(9) Packaging (C:paper tape, E:embossed tape)

(2) Type (T: Metal Composite Thin Film Type)(4) Thicknes (10: 1.0mm)

(6) Inductan (R33: 0.33 uH)

#### RECOMMENDED SOLDERING CONDITION





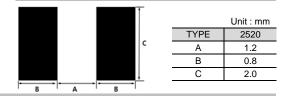
IRON SOLDERING								
Temperature of	280℃max.							
Soldering Iron Tip	200 0 1110.							
Preheating	150°C min.							
Temperature	150 C min.							
Temperature	ΔT≤130℃							
Differential	$\Delta 1 \ge 150$ C							
Soldering Time	3sec max.							
Soluting Third	ssee max.							
Wattage	50W max.							

PACKAGING

Packaging Style	Quantity(pcs/reel)
Embossed Taping	3000 pcs



#### **RECOMMENDED LAND PATTERI**



TYPE	Dimension [mm]						
	L	W	Т	D			
2520	2.5±0.2	2.0±0.2	1.0 max	0.55±0.25			

ltem	Specified Value	Test Condition			
Solderability	More than 90% of terminal electrode should be soldered newly.	After being dipped in flux for 4±1 seconds, and preheated at $150 \sim 180$ °C for $2 \sim 3$ min, the specimen shall be immersed in solder at $245\pm5$ °C for 4±1 seconds.			
Resistance to Soldering	No mechanical damage. Remaining terminal Electrode: 75% min. Inductance change to be within ±20% to the initial.	After being dipped in flux for $4\pm 1$ seconds, and preheated at $150 \sim 180^{\circ}$ for $2 \sim 3$ min, the specimen shall be immersed in solder at $260\pm 5^{\circ}$ for $10\pm 0.5$ seconds.			
Thermal Shock (Temperature Cycle test)	No mechanical damage Inductance change to be within ±20% to the initial.	Repeat 100 cycles under the following conditions. -40±3 °C for 30 min $\rightarrow$ 85±3 °C for 30 min			
High Temp. Humidity Resistance Test	No mechanical damage Inductance change to be within ±20% to the initial	85±2 <sup>°</sup> C, 85%RH, for 500±12 hours. Measure the test items after leaving at normal temperature and humidity for 24 hours.			
Low Temperature Test	No mechanical damage Inductance change to be within ±20% to the initial.	Solder the sample on PCB. Exposure at -55±2°C for 500±12 hours. Measure the test items after leaving at normal temperature and humidity for 24hours.			
High Temperature Test	No mechanical damage Inductance change to be within ±20% to the initial.	Solder the sample on PCB. Exposure at 125±2 °C for 500±12 hours. Measure the test items after leaving at normal temperature and humidity for 24hours.			
High Temp. Humidity Resistance Loading Test	No mechanical damage Inductance change to be within ±20% to the initial	85±2°C, 85%RH, Rated Current for 500±12 hours. Measure the test items after leaving at normal temperature and humidity for 24 hours.			
High Temperature Loading Test	No mechanical damage Inductance change to be within ±20% to the initial	$85\pm2$ °C, Rated Current for 500±12 hours. Measure the test items after leaving at normal temperature and humidity for 24 hours.			
Reflow Test	No mechanical damage Inductance change to be within ±20% to the initial	Peak 260±5 ℃, 3 times			
Vibration Test	No mechanical damage Inductance change to be within ±20% to the initial.	Solder the sample on PCB. Vibrate as apply 10~55Hz, 1.5mm amplitude for 2 hours in each of three(X,Y,Z) axis (total 6 hours).			
	No mechanical damage	Bending Limit; 2mm Test Speed; 1.0mm/sec. Keep the test board at the limit point in 5 sec. PCB thickness : 1.6mm			
Bending Test		20 Unit :mm R340 46 46			
	No indication of peeling shall occur on the terminal electrode.	W(kgf) TIME(sec)			
Terminal Adhesion Test		0.5 10±1			
Drop Test	No mechanical damage Inductance change to be within ±20% to the initial.	Random Free Fall test on concrete plate. 1 meter, 10 drops			
lpeak (AC+DC Load Life)	No mechanical damage Inductance change to be within ±20% to the initial	85±2°C, 85%RH, Load(Ipeak) for 120 hours. (Frequncy:1MHz, Load(Ipeak):1.5hr on / 0.5hr off) Measure the test items after leaving at normal temperature and humidity for 24 hours. * Load(Ipeak) = Irms(max)×1.4			



**Data Sheet** 



## 1. Model : CIGT252010LMR33MNE

### 2. Description

Part no.	Size Thickness [inch/mm] [mm] (max)	Inductance	Inductance tolerance	DC Resistance [mΩ]		Rated DC Current (Isat) [A]		Rated DC Current (Irms) [A]		
		[mm] (max)	[uH]	(%)	Max.	Тур.	Max.	Тур.	Max.	Тур.
CIGT252010LMR33MNE	1008/2520	1.0	0.33	±20	22	17	6.5	7.3	5	5.5

\* Inductance : Measured with a LCR meter 4991A(Agilent) or equivalent (Test Freq. 1MHz, Level 0.1V)

\* DC Resistance : Measured with a Resistance HI-TESTER 3541(HIOKI) or equivalent

\* Maximum allowable DC current : Value defined when DC current flows and the initial value of inductance has decreased by 30% or

when current flows and temperature has risen to 40 °C whichever is smaller. (Reference: ambient temperature is 25 °C±10) (Isat) : Allowable current in DC saturation : The DC saturation allowable current value is specified when the decrease of

the initial inductance value at 30% (Reference: ambient temperature is 25 ℃±10)

(Irms) : Allowable current of temperature rise : The temperature rise allowable current value is specified when temperature of

the inductor is raised 40  $^\circ\!\!{\rm C}$  by DC current. (Reference: ambient temperature is 25  $^\circ\!\!{\rm C}\pm\!10)$ 

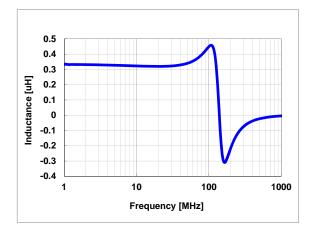
\* Absolute maximum voltage : Absolute maximum voltage DC 20V.

\* Operating temperature range : -40 to +125°C (Including self-temperature rise)

### 3. Characteristics data

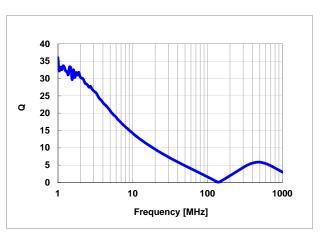
1) Frequency characteristics (Ls)

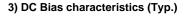
Agilent E4294A +E4991A , 1MHz to 1,000MHz

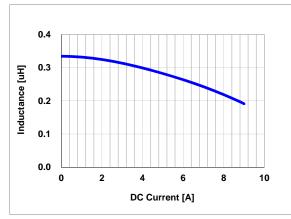


## 2) Frequency characteristics (Q)

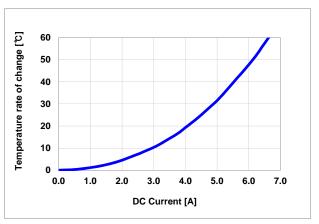
Agilent E4294A +E4991A , 1MHz to 1,000MHz







4)Temperature characteristics (Typ.)



Any data in this sheet are subject to change, modify or discontinue without notice The data sheets include the typical data for design reference only. If there is any question regarding the data sheets, please contact our sales personnel or application engineers